



P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BV _{DSS} | RDS(ON) max | I _D T _A = +25°C |
|-------------------|--------------------------------|------------------------------------------|
| -20V | 1.0Ω @ V _{GS} = -4.5V | -600mA |
| | 1.5Ω @ V _{GS} = -2.5V | -500mA |
| | 2.0Ω @ V _{GS} = -1.8V | -400mA |
| | 3.0Ω @ V _{GS} = -1.5V | -250mA |

Description

This new generation MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

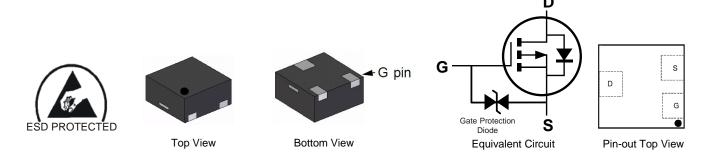
- DC-DC Converters
- Power Management Functions

Features

- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)}, -1.0V Max
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: X1-DFN1212-3
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.005 grams (Approximate)



Ordering Information (Note 4)

| Part Number | Case | Packaging |
|--------------|--------------|------------------|
| DMP21D6UFD-7 | X1-DFN1212-3 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



P16 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: E = 2017) M = Month (ex: 9 = September)

Date Code Key

| Year | 2017 | 2018 | 20 | 19 | 2020 | 2021 | 2022 | 2023 | 20 | 24 | 2025 | 2026 |
|-------|------|------|-----|-----|------|------|------|------|-----|-----|------|------|
| Code | Е | F | (| 3 | Н | | J | K | l | - | М | N |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|-----------------------------------------------------------|-----------------|--------------|------|
| Drain-Source Voltage | V_{DSS} | -20 | V |
| Gate-Source Voltage | V_{GSS} | ±8 | V |
| Continuous Drain Current (Note 6) V _{GS} = -4.5V | Ι _D | -600 -500 | mA |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%) | I _{DM} | -2 | Α |
| Maximum Body Diode Continuous Current | Is | -800 | mA |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit | |
|--------------------------------------------------|--------------|----------------------------------|-------------|------|
| Total Power Dissipation (Note 5) | | P_{D} | 0.4 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Steady State | $R_{	heta JA}$ | 280 | °C/W |
| Total Power Dissipation (Note 6) | | P _D | 0.8 | W |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State | $R_{	heta JA}$ | 140 | °C/W |
| Operating and Storage Temperature Range | | T _{J,} T _{STG} | -55 to +150 | °C |

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|--------------------------------------------------------|---------------------|------|-------|------|------|---------------------------------------------|--|
| OFF CHARACTERISTICS (Note 7) | | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | -20 | _ | _ | V | $V_{GS} = 0V$, $I_D = -1mA$ | |
| Zero Gate Voltage Drain Current T _J = +25°C | I _{DSS} | - | _ | -100 | nA | $V_{DS} = -20V, V_{GS} = 0V$ | |
| Gate-Source Leakage | I _{GSS} | - | _ | ±10 | μΑ | $V_{GS} = \pm 8V$, $V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 7) | | | | | | | |
| Gate Threshold Voltage | V _{GS(TH)} | -0.5 | _ | -1.0 | V | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$ | |
| | | | 0.7 | 1.0 | | $V_{GS} = -4.5V, I_D = -100mA$ | |
| | | | 0.9 | 1.5 | | $V_{GS} = -2.5V, I_{D} = -80mA$ | |
| Static Drain-Source On-Resistance | R _{DS(ON)} | _ | 1.2 | 2.0 | Ω | $V_{GS} = -1.8V, I_{D} = -40mA$ | |
| | , , | _ | 1.5 | 3.0 | | $V_{GS} = -1.5V, I_D = -30mA$ | |
| | | _ | 5 | _ | | $V_{GS} = -1.2V, I_{D} = -1mA$ | |
| Diode Forward Voltage | V_{SD} | _ | -0.75 | -1.2 | V | $V_{GS} = 0V, I_{S} = -330mA$ | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | | | | |
| Input Capacitance | C _{iss} | 1 | 46.1 | _ | | | |
| Output Capacitance | Coss | _ | 7.2 | _ | pF | $V_{DS} = -10V, V_{GS} = 0V,$ f = 1.0MHz | |
| Reverse Transfer Capacitance | C _{rss} | _ | 4.9 | _ | | I = 1.0WI IZ | |
| Total Gate Charge V _{GS} = -4.5V | Q_{g} | _ | 0.5 | _ | | V 40V I 050v A | |
| Total Gate Charge V _{GS} = -8V | Q_g | | 0.8 | _ | nC | | |
| Gate-Source Charge | Q_{gs} | _ | 0.1 | _ | IIC | $V_{DS} = -10V, I_{D} = -250mA$ | |
| Gate-Drain Charge | Q _{gd} | _ | 0.1 | _ | | | |
| Turn-On Delay Time | t _{D(ON)} | | 8.5 | _ | | V 9V V 9.5V | |
| Turn-On Rise Time | t _R | _ | 4.3 | _ | 1 | $V_{DD} = -3V$, $V_{GS} = -2.5V$, | |
| Turn-Off Delay Time | t _{D(OFF)} | | 20.2 | _ | ns | $R_L = 300\Omega, R_G = 25\Omega,$ | |
| Turn-Off Fall Time | t _F | _ | 19.2 | _ | | $I_D = -100 \text{mA}$ | |

Notes:

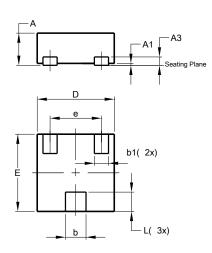
- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to product testing.



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1212-3

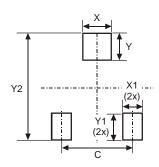


| X1-DFN1212-3 | | | | | | | |
|----------------------|------|------|------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.47 | 0.53 | 0.50 | | | | |
| A1 | 0 | 0.05 | 0.02 | | | | |
| А3 | 1 | - | 0.13 | | | | |
| b | 0.27 | 0.37 | 0.32 | | | | |
| b1 | 0.17 | 0.27 | 0.22 | | | | |
| D | 1.15 | 1.25 | 1.20 | | | | |
| Е | 1.15 | 1.25 | 1.20 | | | | |
| е | - | - | 0.80 | | | | |
| L | 0.25 | 0.35 | 0.30 | | | | |
| All Dimensions in mm | | | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1212-3



| Dimensions | Value (in mm) |
|------------|---------------|
| С | 0.80 |
| Х | 0.42 |
| X1 | 0.32 |
| Y | 0.50 |
| Y1 | 0.50 |
| Y2 | 1.50 |



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